

/ Descriptions

KF \$0) GE G Silicon PNP transistor in a TO-92 Plastic Package.

/ Features

BJ: O+,
Complementary pair with KSC945.

/ Applications

Low frequency amplifier applications.

/ Equivalent Circuit



/ Pinning



PIN1 Collector PIN 2 Base PIN 3 Emitter

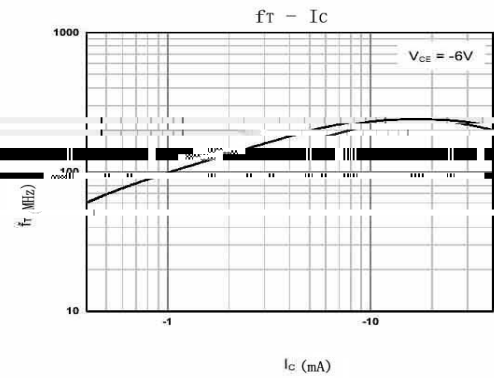
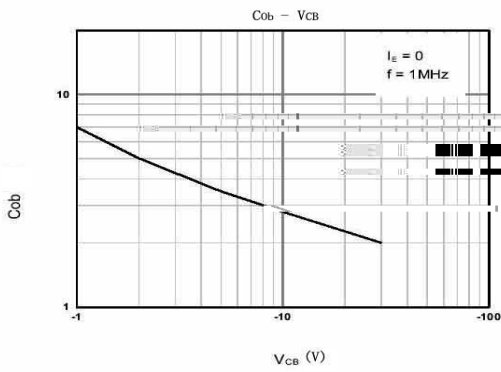
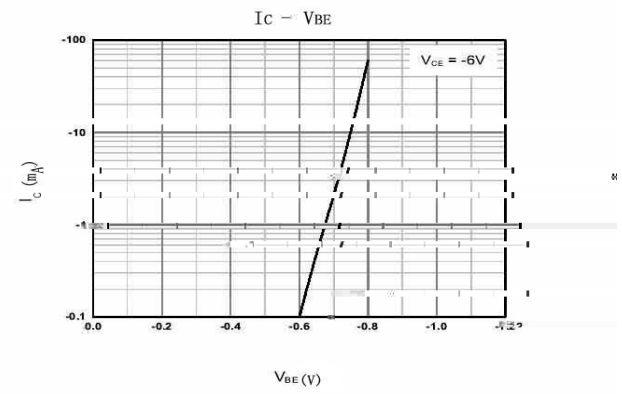
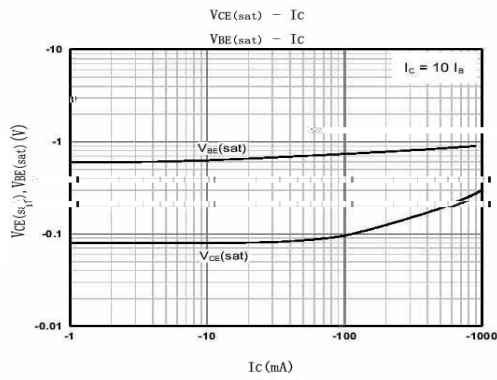
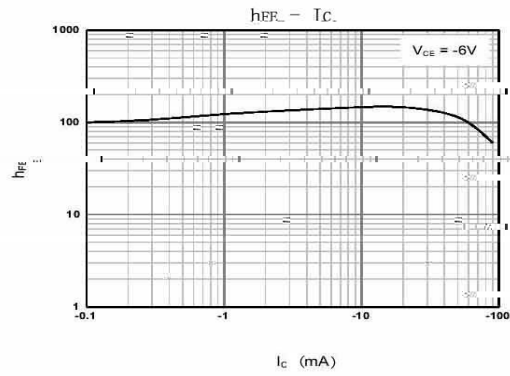
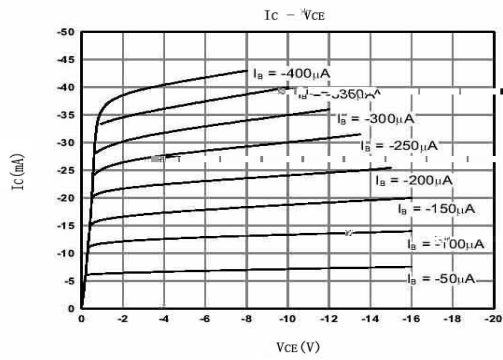
/ hFE Classifications & Marking

h _{FE} Classifications Symbol	R	O	Y	G	L
h _{FE} Range	40~80	70~140	120~140	200~400	350~700

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-60	V
Collector to Emitter Voltage	V_{CEO}	-50	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-150	mA
Collector Power Dissipation	P_C	250	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter Symbol

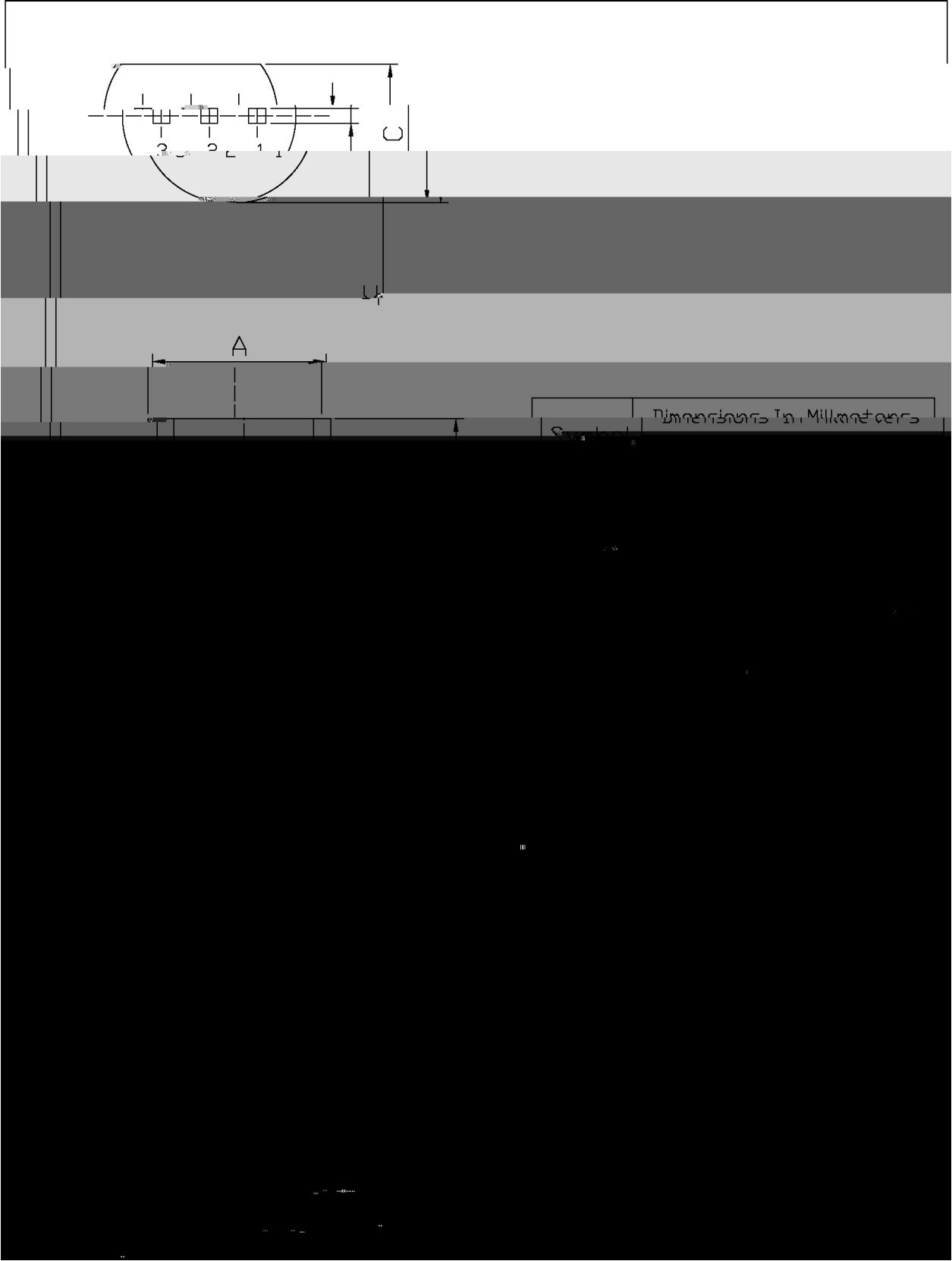
/ Electrical Characteristic Curve



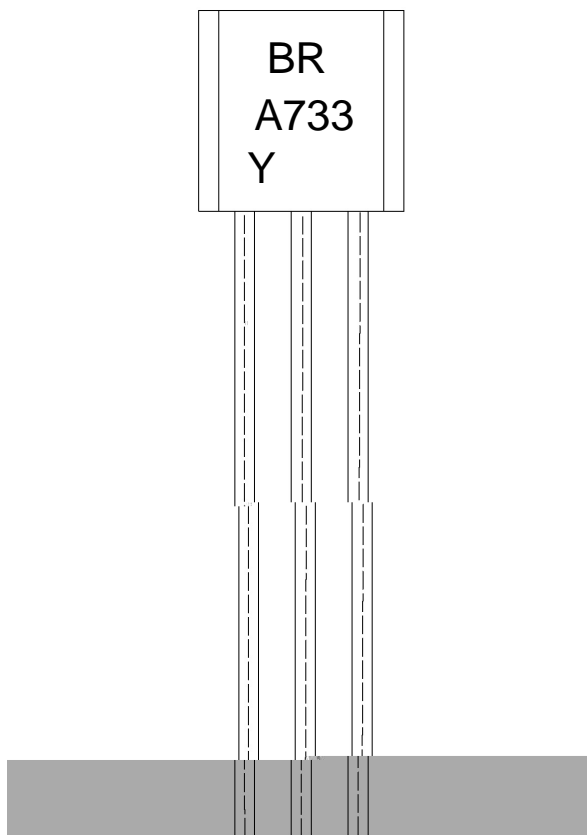
/ Package Dimensions

T0-92

Unit: mm



/ Marking Instructions



9| 1

8. **

P1

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Note:

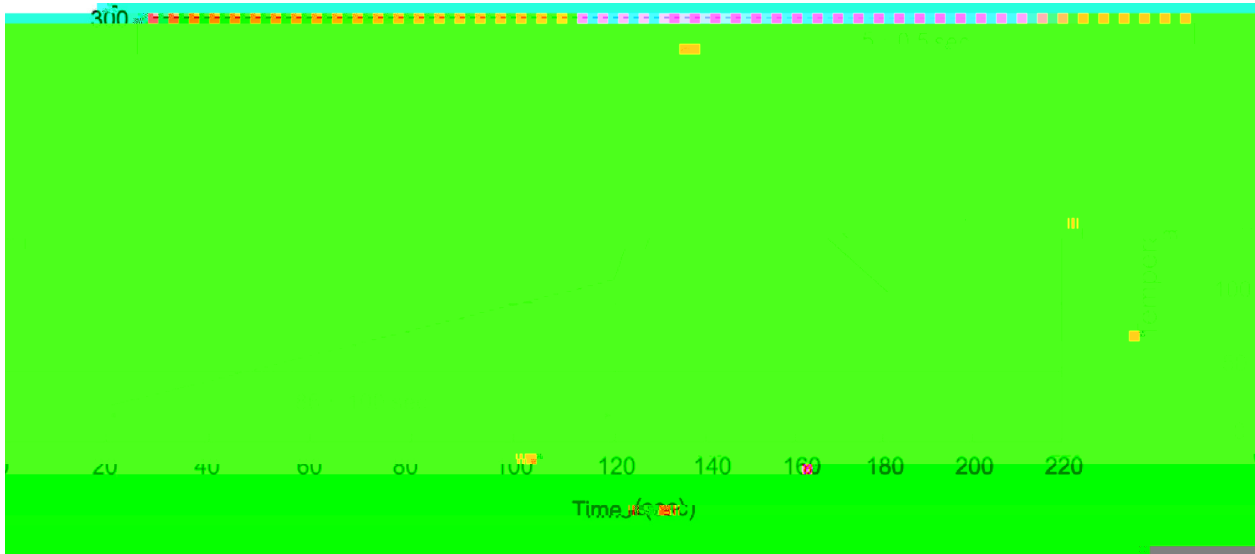
BR: Company Code.

A733: Product Type.

Y: h_{FE} Classifications Symbol

****: Lot No. Code,code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|--------|-----|------------|----------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255..5 | | 5..0.5sec; | | 2.Peak Temp.:255..5 , Duration:5..0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270..5 10..1 sec. Temp:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units				Dimension		(unit mm ³)

/ AMMO

Package Type	Units				Dimension		(unit mm ³)

/ Notices